

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT																				
NATURE OF CONVEYANCE:	ASSIGNMENT																				
CONVEYING PARTY DATA																					
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Shih-Chieh Chang</td> <td>01/06/2012</td> </tr> <tr> <td>Jian-Shin Tsai</td> <td>01/06/2012</td> </tr> <tr> <td>Chih-Chang Huang</td> <td>01/06/2012</td> </tr> <tr> <td>Ing-Ju Lee</td> <td>01/06/2012</td> </tr> <tr> <td>Ching-Yao Sun</td> <td>01/06/2012</td> </tr> <tr> <td>Jyun-Ru Wu</td> <td>01/06/2012</td> </tr> <tr> <td>Ching-Che Huang</td> <td>01/06/2012</td> </tr> <tr> <td>Szu-An Wu</td> <td>01/06/2012</td> </tr> <tr> <td>Ying-Lang Wang</td> <td>01/06/2012</td> </tr> </tbody> </table>		Name	Execution Date	Shih-Chieh Chang	01/06/2012	Jian-Shin Tsai	01/06/2012	Chih-Chang Huang	01/06/2012	Ing-Ju Lee	01/06/2012	Ching-Yao Sun	01/06/2012	Jyun-Ru Wu	01/06/2012	Ching-Che Huang	01/06/2012	Szu-An Wu	01/06/2012	Ying-Lang Wang	01/06/2012
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Ying-Lang Wang	01/06/2012																				
RECEIVING PARTY DATA																					
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.																				
Street Address:	No. 8, Li-Hsin Rd. 6																				
Internal Address:	Science-Based Industrial Park																				
City:	Hsin-Chu																				
State/Country:	TAIWAN																				
Postal Code:	300-77 R.O.C.																				
PROPERTY NUMBERS Total: 1																					
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13420279</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13420279																
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Application Number:	13420279																				
CORRESPONDENCE DATA																					
Fax Number:	(972)732-9218																				
Phone:	972-732-1001																				
Email:	docketing@slater-matsil.com																				
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>																					
Correspondent Name:	Slater & Matsil, L.L.P.																				

CH \$40.00 13420279

Address Line 1: 17950 Preston Road
Address Line 2: Suite 1000
Address Line 4: Dallas, TEXAS 75252

ATTORNEY DOCKET NUMBER:	TSM11-1379
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NAME OF SUBMITTER:	Kasey Edwards
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Total Attachments: 3 source=TSM11-1379_Assignment#page1.tif source=TSM11-1379_Assignment#page2.tif source=TSM11-1379_Assignment#page3.tif
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ATTORNEY DOCKET NO.
TSM11-1379

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. (TSMC), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TSMC, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TSMC, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to TSMC, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TSMC, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TSMC, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	<i>Metal Shielding Layer in Backside Illumination Image Sensor Chips and Methods for Forming the Same</i>			
SIGNATURE OF INVENTOR AND NAME	<i>Shih-Chieh Chang</i> Shih-Chieh Chang	<i>Jian-Shin Tsai</i> Jian-Shin Tsai	<i>Chih-Chang Huang</i> Chih-Chang Huang	<i>Ing-Ju Lee</i> Ing-Ju Lee
DATE	<i>2012.01.06</i>	<i>2012.01.06</i>	<i>2012.01.06</i>	<i>2012.01.06</i>
RESIDENCE (City, County, State)	Taipei City, Taiwan	Tainan City, Taiwan	Chiayi City, Taiwan	Tainan City, Taiwan

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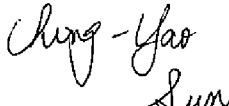
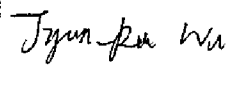
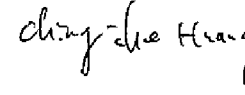
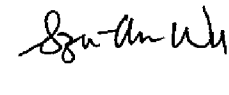
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SIGNATURE OF INVENTOR AND NAME	 Ching-Yao Sun	 Jyun-Ru Wu	 Ching-Che Huang	 Szu-An Wu
DATE	2012.01.06.	2012.01.06	2012.01.06	2012.01.06
RESIDENCE (City, County, State)	Kaohsiung City, Taiwan	Tainan City, Taiwan	New Taipei City, Taiwan	Tainan City, Taiwan

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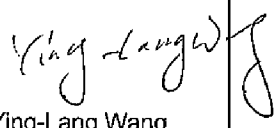
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SIGNATURE OF INVENTOR AND NAME	 Ying-Lang Wang		
DATE	2012, 01, 06		
RESIDENCE (City, County, State)	Tien-Chung Village, Taiwan		